

**IN THE CLAIMS:**

1           1.       (Original) A wire loop comprising:

2                   a wire connecting a first bonding point and a second bonding point therethrough;

3                   said wire including a ball bonded to said first bonding point, a neck portion  
4 adjacent to said ball and a major portion extending from said neck portion to said second  
5 bonding point;

6                   wherein said major portion of said wire has a crushed part formed in proximity to  
7 said neck portion by crushing the part of said wire together with a top portion of said ball.

1           2.       (Original) The wire loop as defined in claim 1, wherein said neck portion

2 includes a first kink formed by a part of said neck portion being doubled over.

1           3.       (Original) The wire loop as defined in claim 1, wherein said major portion of said

2 wire includes a horizontal portion extending in a substantially horizontal direction from said  
3 neck portion and an inclined portion which extends from said horizontal portion to said second  
4 bonding point and which has an end thereof bonded to said second bonding point; and

5                   said inclined portion is connected to said horizontal portion through a second kink  
6 formed in a part of said wire therebetween.

1           4.       (Original) The wire loop as defined in claim 2, wherein said major portion of said

2 wire includes a horizontal portion extending in a substantially horizontal direction from said  
3 neck portion and an inclined portion which extends from said horizontal portion to said second  
4 bonding point and which has an end thereof bonded to said second bonding point; and

5                   said inclined portion is connected to said horizontal portion through a second kink  
6 formed in a part of said wire therebetween.

1           5.       (Original) The wire loop as defined in claim 2, wherein said neck portion  
2 includes at least one additional doubled over kink like said first kink.

1           6-13.     (Cancelled)

1           14.     (Original) A semiconductor device comprising:  
2                   a first bonding point;  
3                   a second bonding point; and  
4                   a wire bonded to said first bonding point and said second bonding point to  
5 connect said first bonding point and said second bonding point therethrough;  
6                   wherein said wire includes a ball bonded to said first bonding point, a neck  
7 portion adjacent to said ball and a major portion extending from said neck portion to said second  
8 bonding point; and  
9                   wherein said major portion of said wire has a crushed part formed in proximity to  
10 said neck portion by crushing the part of said wire together with a top portion of said ball.

1           15.     (Original) The semiconductor device as defined in claim 14, wherein said neck  
2 portion includes a first kink formed by a part of said neck portion being doubled over.

1           16.     (Original) The semiconductor device as defined in claim 15, wherein said neck  
2 portion includes at least one additional doubled over kink like said first kink.

1           17.   (New) An improved wire loop connector for electrical connection between a  
2 semiconductor device and a lead frame comprising:

3                   a wire body of a predetermined length;

4                   a first end of the wire body for electrical connection with the semiconductor  
5 device having an immediately adjacent first overlaid length of the wire body to double the  
6 overall thickness of the wire body at the electrical connection; and

7                   a second distal end of the wire body for electrical connection with the lead frame  
8 having a thickness of the wire body wherein the height of the wire body relative to a distance  
9 above the semiconductor device is restricted.

1           18.   (New) The improved wire loop connection of Claim 17 further including at the  
2 first end of the wire body a second overlaid length of the wire body wherein a thickness is  
3 quadruple the overall thickness of the wire body.

1           19.   (New) The improved wire loop connection of Claim 18 wherein the wire body  
2 has been bent three times to integrally form the quadruple overall thickness with each bent length  
3 closed upon another length of the wire body.